



SS12 THRU SS1200

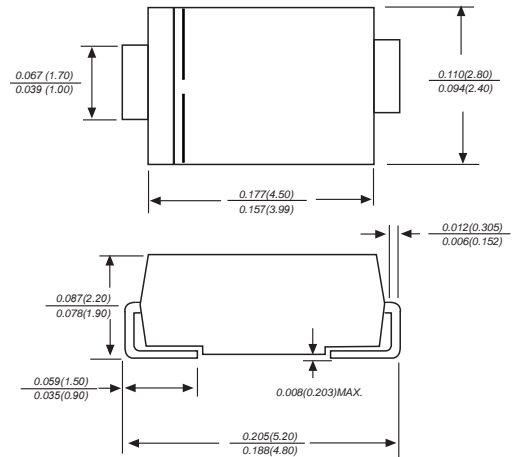
Reverse Voltage - 20 to 200 Volts Forward Current - 1.0 Ampere

SURFACE MOUNT SCHOTTKY BARRIER RECTIFIER

Features

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ For surface mounted applications
- ◆ Metal silicon junction, majority carrier conduction
- ◆ Low power loss, high efficiency
- ◆ Built-in strain relief, ideal for automated placement
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed:
250 °C/10 seconds at terminals

DO-214AC/SMA



Dimensions in inches and (millimeters)

Mechanical Data

Case : JEDEC DO-214AC/SMA molded plastic body
 Terminals : Solderable per MIL-STD-750, Method 2026
 Polarity : Color band denotes cathode end Mounting
 Position : Any
 Weight : 0.002 ounce, 0.07 grams

Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	SS12	SS13	SS14	SS15	SS16	SS18	SS110	SS1150	SS1200	UNITS
		MDD SS12	MDD SS13	MDD SS14	MDD SS15	MDD SS16	MDD SS18	MDD SS110	MDD SS1150	MDD SS1200	
Maximum repetitive peak reverse voltage	V_{RRM}	20	30	40	50	60	80	100	150	200	V
Maximum RMS voltage	V_{RMS}	14	21	28	35	42	56	70	105	140	V
Maximum DC blocking voltage	V_{DC}	20	30	40	50	60	80	100	150	200	V
Maximum average forward rectified current at TL (see fig.1)	I_{AV}	1.0									A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	30									A
Maximum instantaneous forward voltage at 1.0A	V_F	0.45	0.55	0.70			0.85		0.9	V	
Maximum DC reverse current $T_A=25^\circ C$ at rated DC blocking voltage $T_A=125^\circ C$	I_R	0.5					0.2				mA
		10.0					5.0	2.0			
Typical junction capacitance (NOTE 1)	C_J	110			90						pF
Typical thermal resistance (NOTE 2)	$R_{\theta JA}$	88.0									°C/W
Operating junction temperature range	T_J	-50 to +125					-50 to +150				°C
Storage temperature range	T_{STG}	-50 to +150									°C

Note: 1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.
 2. P.C.B. mounted with 0.2x0.2" (5.0x5.0mm) copper pad areas



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Typical Characteristics

Fig.1 Forward Current Derating Curve

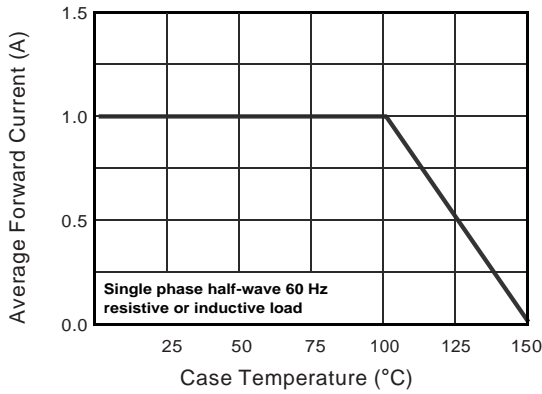


Fig.2 Typical Reverse Characteristics

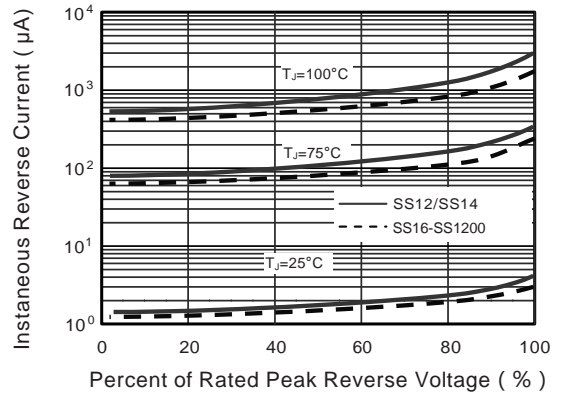


Fig.3 Typical Forward Characteristic

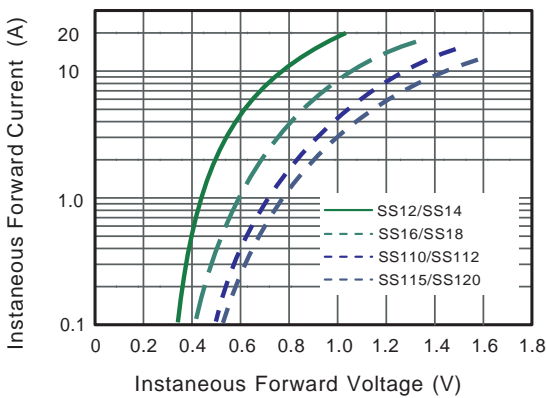


Fig.4 Typical Junction Capacitance

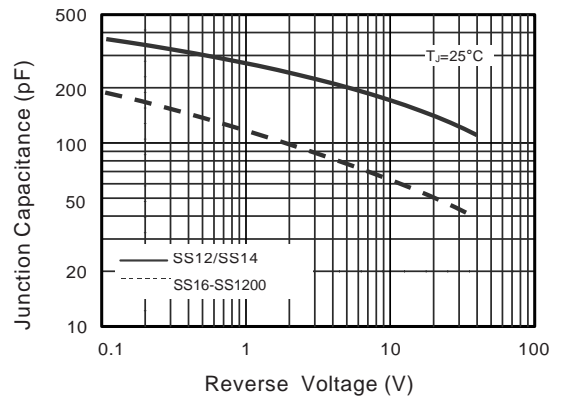


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current

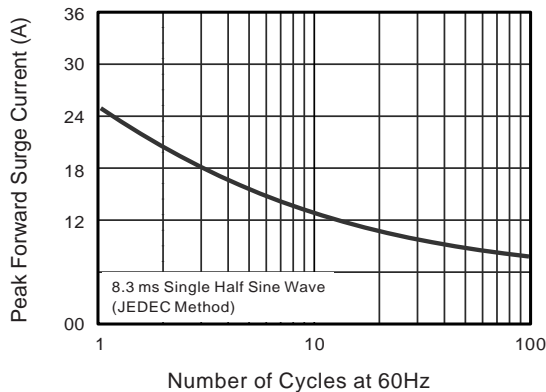
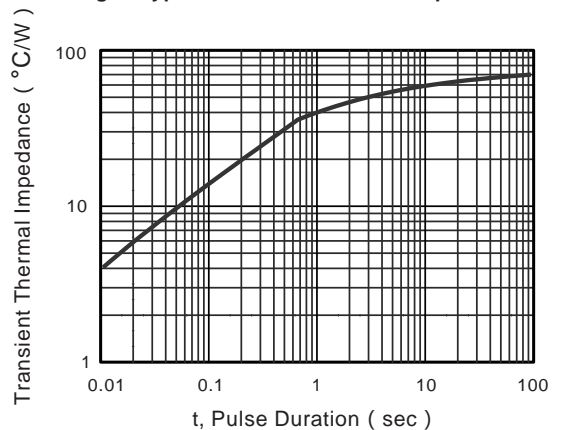


Fig.6- Typical Transient Thermal Impedance



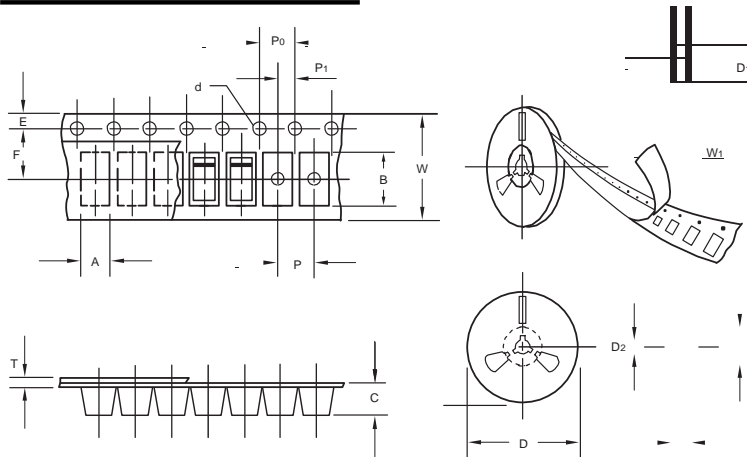
The curve above is for reference only.



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Packing information



unit:mm

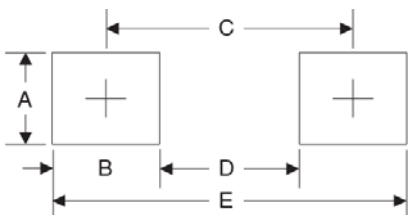
Item	Symbol	Tolerance	SMA
Carrier width	A	0.1	2.80
Carrier length	B	0.1	5.33
Carrier depth	C	0.1	2.36
Sprocket hole	d	0.05	1.50
13" Reel outside diameter	D	2.0	330.00
13" Reel inner diameter	D ₁	min	50.00
7" Reel outside diameter	D	2.0	178.00
7" Reel inner diameter	D ₁	min	62.00
Feed hole diameter	D ₂	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	5.50
Punch hole pitch	P	0.1	4.00
Sprocket hole pitch	P ₀	0.1	4.00
Embossment center	P ₁	0.1	2.00
Overall tape thickness	T	0.1	0.28
Tape width	W	0.3	12.00
Reel width	W ₁	1.0	18.00

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA, (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SMA	7"	2,000	4.0	4,000	183*155*183	178	382*356*392	80,000	16.0
SMA	11"	5,000	4.0	10,000	290*290*38	330	310*310*360	80,000	11.0
SMA	13"	7,500	4.0	15,000	335*335*38	330	350*330*360	120,000	14.5

Suggested Pad Layout



Symbol	Unit (mm)	Unit (inch)
A	1.68	0.066
B	1.52	0.060
C	3.90	0.154
D	2.41	0.095
E	5.45	0.215

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